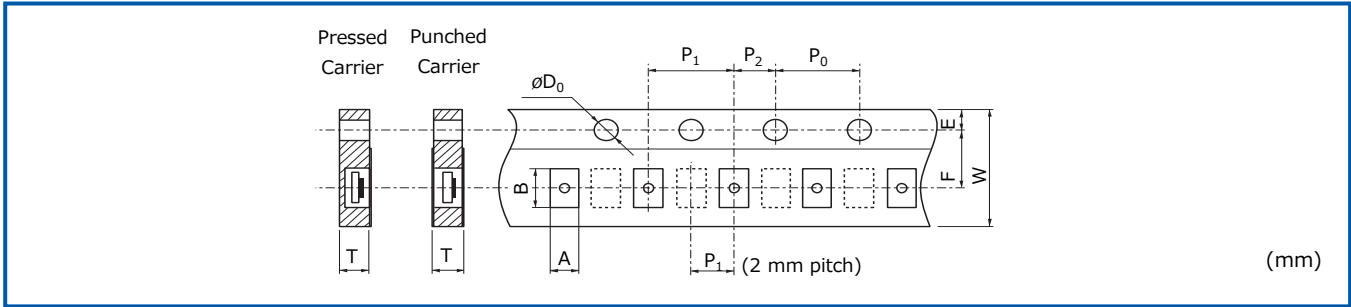


**Packaging Methods (Taping)**

● Standard Quantity

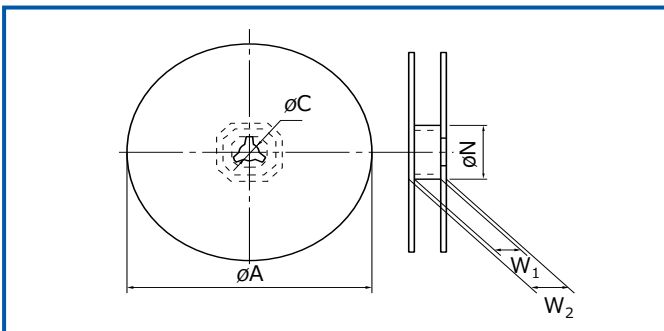
Part Number	Size (inch)	Type	Kind of Taping	Pitch (P <sub>1</sub> )	Quantity
EZAEG1N	0201	Single	Pressed Carrier Taping	2 mm	15,000 pcs / reel
EZAEG2A,2N	0402				10,000 pcs / reel
EZAEG3A	0603				5,000 pcs / reel
EZAEG3W	0603	Array	Punched Carrier Taping	4 mm	4,000 pcs / reel
EZAEGCA	0805				5,000 pcs / reel

● Carrier Taping



Part Number	Size(inch)	A	B	W	F	E	P <sub>1</sub>	P <sub>2</sub>	P <sub>0</sub>	øD <sub>0</sub>	T
EZAEG1N	0201	0.38±0.05	0.68±0.05	8.00±0.20	3.50±0.05	1.75±0.10	2.00±0.10	2.00±0.05	4.00±0.10	1.5 <sup>+0.1</sup> <sub>0</sub>	0.42±0.05
EZAEG2A,2N	0402	0.70±0.05	1.20±0.05				0.60±0.05				
EZAEG3A	0603	1.10±0.10	1.90±0.10				0.70±0.05				
EZAEG3W	0603	0.91±0.10	1.82±0.10	8.00±0.20	3.50±0.05	1.75±0.10	4.00±0.10	2.00±0.05	4.00±0.10	1.5 <sup>+0.1</sup> <sub>0</sub>	1.08±0.10
EZAEGCA	0805	1.55±0.15	2.30±0.20				0.85±0.05				

● Taping Reel



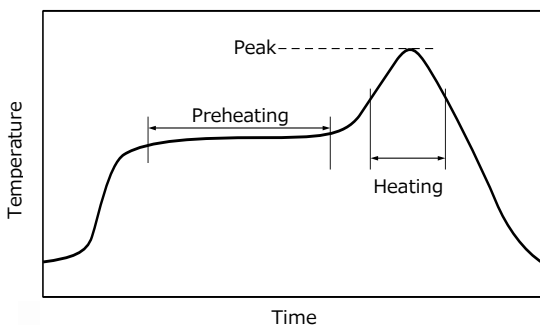
Dimensions(mm)		
øA	øN	øC
180.0 <sup>0</sup> <sub>-1.5</sub>	60.0 <sup>+1.0</sup> <sub>0</sub>	13.0±0.2
Dimensions(mm)		
W <sub>1</sub>	W <sub>2</sub>	
9.0 <sup>+1.0</sup> <sub>0</sub>	11.4±1.0	

**Recommended Soldering Conditions**

Recommendations and precautions are described below

● Recommended soldering conditions for reflow

- Reflow soldering shall be performed a maximum of two times.
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example : Sn/Pb )

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu )

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s